



PTO/US/OBA (10-01)
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Substitute for form 1449A/PTO			Complete if Known		
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)			Application Number	09/653,411	
			Filing Date	August 31, 2000	
			First Named Inventor	Whonchee Lee	
			Art Unit	2815	
			Examiner Name	Joseph H. Nguyen	
Sheet	1	of	3	Attorney Docket Number	M4065.0361/P361

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Examiner Initials*	Class No.	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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Sheet 2 of 3	Attorney Docket Number	M4065.0361/P361	

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